ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoo nternational and Pan-Ameri	kburn, Illinois	. All rights reserv	tion with lower	level p	arts, the	declaratio	n encomp	asses all l		aterials for	r which t	e item is an assembly he manufacturer has declaration.		
1/32-2 1.1		Web Site for Informat		:-1752 Standa	rd		n Type * ribute	-		aration Class * s 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa						
Supplier Information																
Company Name *		Company Unique ID		Unique ID Authority			onse Date	*	R	Response Document ID						
Cypress Semiconductor	Corp	Cypress				2009-	08-25									
Contact Name *	Phone - Con	Email	- Contac	t *												
Richard Oshiro Quality Systems Director				408 943 2102	rgo@	cypress.c	om		Duplicate Contact -> Authorized Representative							
Authorized Representati	ve *	Title - Representative	Э	Phone - Representative *			- Repres	entative	* S	Supplier Comments or URL for Additional Information						
Glorioso Lutrinia EH & S Manager				632 812 8161			cypress.c	om								
Requester Item Number	Mfr Item Number		Mfr Item Name	Effective Date Versi			Manufact	uring Site	Weight *	U	ОМ	Unit Type				
		VFBGA 100		VFBGA 100	2009-08-25			AIT Indo	nesia	70	m	g	Each			
Alternate Recommenda	ation							Alternate Item C			Comments Package QTP No. 071202					
Manufacturing Proces	ss In	formation				•										
Terminal Plating / Grid Array Material Terminal B				ase Alloy	ating	ating Peak Process Body Tempe			ıre Max Ti	me at Peak Te	mperature	Number	of Reflow Cycles			
Tin/Silver/Copper (Sn/Ag/Cu) CU Alloy			1	3		260			20 seconds 3							
Comments Compliant to RoHS and	Halo	gen Requirements, (6x6x1.0 m	m, BZ100												

Save the fields in Import fields from a Clear all of the Lock the fields on this **Export Data** Import Data Reset Form Lock Supplier Fields this form to a file file into this form fields on this form form to prevent changes **RoHS Material Composition Declaration Declaration Type *** Detailed Rohs Directive Rohs Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenvls (PBB). Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium 2002/95/EC Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply. 1 - Item(s) does not contain RoHS restricted substances per the definition above Supplier Acceptance * Accepted **RoHS Declaration *** Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. **Declaration Signature**

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Mojak	Unit of		Laural	Substance Category			Cubatanaa	CAS		Weight	Unit of	Tolerance		РРМ
	Name		Material	Weight	Measure		Level	Substance Category			Substance	CAS	Exempt	weight	Measure	-	+	PPW
+1 -1	Substrate	+M -M	Base Material	2.8	mg	+C -C	Supplier	Au, metal & alloy	+S	-\$	Au, metal & alloy	7440-57-5		0.0207	mg			296
						+C -C	Supplier	Ni, metal & alloy	+S	-S	Ni, metal & alloy	65997-17-3		0.0952	mg			1,359
						+C -C	Supplier	Cu, metal & alloy	+S	-S	Cu, metal & alloy	7440-50-8		0.7154	mg			10,216
						+C -C	Supplier	Acrylic Resin	+S	-S	Acrylic Resin	Trade Secre		0.0216	mg			308
						+C -C	Supplier	Phthalcyanine Blue, C	+S	-s	Phthalcyanine Blue, Org	Trade Secre		0.0003	mg			4
						+C -C	Supplier	Fillers (Barium Sulfat	+S	-s	Fillers (Barium Sulfate,	Trade Secre		0.0165	mg			236
						+C -C	Supplier	Aromatic Carbonyl C	+S	-s	Aromatic Carbonyl Com	Trade Secre		0.0022	mg			32
						+C -C	Supplier	Amine Compound	+S	-s	Amine Compound	Trade Secre		0.0036	mg			52
						+C -C	Supplier	Levelling Agents & O	+S	-S	Levelling Agents & Oth	Trade Secre		0.0008	mg			12
						+C -C	Supplier	Acrylic Monomer	+S	-S	Acrylic Monomer	Trade Secre		0.0028	mg			40
						+C -C	Supplier	Epoxy Resin	+S	-S	Epoxy Resin	29690-82-2;		0.0092	mg			132
						+C -C	Supplier	Barium Sulfate	+S	-S	Barium Sulfate	Trade Secre		0.0039	mg			56
						+C -C	Supplier	Organic Fillers	+S	-S	Organic Fillers	Trade Secre		0.0008	mg			12
						+C -C	Supplier	BT Resin	+S	-S	BT Resin	13676-54-5;		0.84	mg			11,995
						+C -C	Supplier	Fibrous-glass-wool	+S	-S	Fibrous-glass-wool	65997-17-3		1.0668	mg			15,233
+1 -1	Solder Ball	+M -M	External Plating	41.45	mg	+C -C	Supplier	Tin	+S	-S	Tin	7440-31-5		40.8283	mg			583,01
						+C -C	Supplier	Silver	+S	-S	Silver	7440-22-4		0.4145	mg			5,919
						+C -C	Supplier	Copper	+S	-S	Copper	7440-50-8		0.2073	mg			2,959
+1 -1	Die Attach	+M -M	Adhesive	6.51	mg	+C -C	Supplier	Ag	+S	-S	Ag	7440-22-4		4.557	mg			65,072
						+C -C	Supplier	Epoxy Resin	+S	-S	Epoxy Resin	Trade Secre		0.3255	mg			4,648
						+C -C	Supplier	Diester	+S	-S	Diester	Trade Secre		0.651	mg			9,296
						+C -C	Supplier	Polymeric Resin	+S	-S	Polymeric Resin	Trade Secre		0.3255	mg			4,648
						+C -C	Supplier	Functionalized Ester	+S	-S	Functionalized Ester	Trade Secre		0.651	mg			9,296

+1 -1	Die	+M -M	Circuit	4	mg	+C	-C	Supplier	Silicon	+S	-s	Silicon	7440-21-3	4	mg	57,118
+1 -1	Wire	+M -M	Interconnect	1.75	mg	+C	-C	Supplier	Gold	+S	-s	Gold	7440-57-5	1.75	mg	24,989
+1 -1	Mold Compound	+M -M	Encapsulation	13.52	mg	+C	-C	Supplier	Fused Silica	+S	-s	Fused Silica	60676-86-0	12.844	mg	183,40
						+C	-C	Supplier	Epoxy Resin	+S	-s	Epoxy Resin	Trade Secre	0.2704	mg	3,861
						+C	-C	Supplier	Phenol Resin	+S	-s	Phenol Resin	Trade Secre	0.0676	mg	965
						+C	-C	Supplier	Phenol Novolac	+S	-s	Phenol Novolac	9003-35-4	0.1352	mg	1,931
						+C	-C	Supplier	Metal Hydroxide	+S	-s	Metal Hydroxide	Trade Secre	0.1352	mg	1,931
						+C	-C	Supplier	Carbon Black	+S	-s	Carbon Black	1333-86-4	0.0676	mg	965